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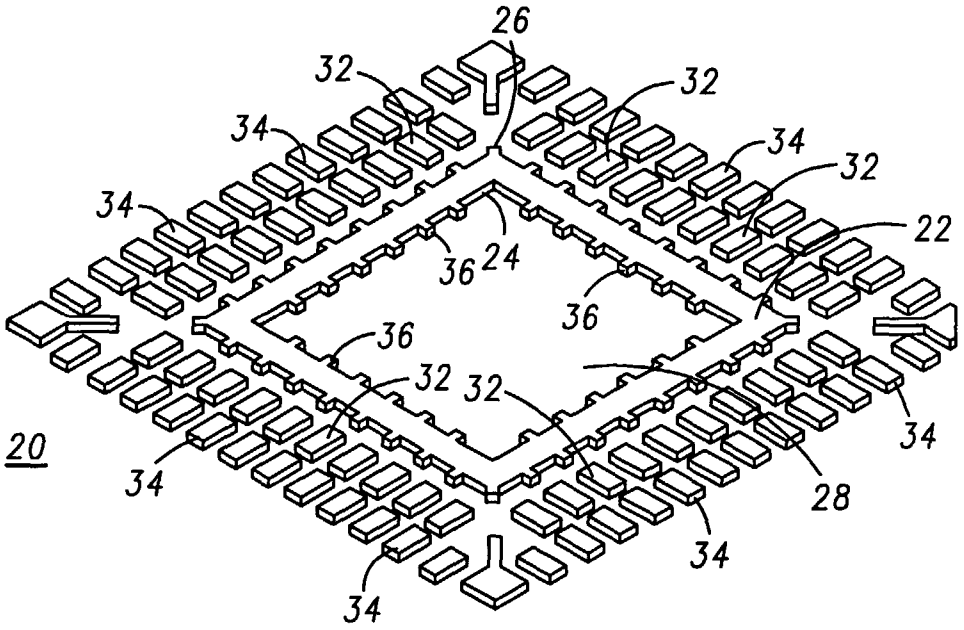
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(54) Title: MULTI-ROW LEADFRAME



(57) Abstract: A leadframe (20) for a semiconductor device includes a paddle ring (22) having an inner perimeter (24), an outer perimeter (26), and a cavity (28) located within the inner perimeter (24) for receiving an integrated circuit die (30). A first row of terminals (32) surrounds the outer perimeter (26) and a second row of terminals (34) surrounds the first row of terminals (32). Each of the terminals of the first row of terminals (32) is individually connected to the paddle ring (22) and each of the terminals of the second row of terminals (34) is connected to one side of a connection bar (78, 79), which is connected to one of the terminals of the first row (32) or to the paddle ring (22).

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